

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ011NE2LS5I	**Issued**	27. April 2022
MA#	MA005736873		
Package	PG-TSDSON-8-34	**Weight***	35.92 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.629	1.75	1.75	17512	17512
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		100	
	non noble metal	zinc	7440-66-6	0.014	0.04		401	
	non noble metal	iron	7439-89-6	0.288	0.80		8028	
	non noble metal	copper	7440-50-8	11.710	32.60	33.45	325983	334512
wire	non noble metal	copper	7440-50-8	0.013	0.04	0.04	354	354
encapsulation	organic material	carbon black	1333-86-4	0.035	0.10		977	
	plastics	epoxy resin	-	1.807	5.03		50296	
	inorganic material	silicondioxide	60676-86-0	15.700	43.70	48.83	437040	488313
leadfinish	non noble metal	tin	7440-31-5	0.395	1.10	1.10	11003	11003
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	566	566
solder	non noble metal	tin	7440-31-5	0.019	0.05		522	
	noble metal	silver	7440-22-4	0.023	0.07		652	
	non noble metal	lead	7439-92-1	0.895	2.49	2.61	24902	26076
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			36	
	non noble metal	iron	7439-89-6	0.004	0.01		119	
	non noble metal	copper	7440-50-8	4.267	11.88	11.89	118791	118946
heatspreader	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	iron	7439-89-6	0.000			3	
	non noble metal	copper	7440-50-8	0.097	0.27	0.27	2714	2718
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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